

The product using material and processing must conform to the "WL-PZ-001"HSF technical standard control requirements



NOTE:

- 1.MATERIAL SPECIFICATION:
 - 1-1.HOUSING: LCP UL94V-0
 - 1-2.SHELL: COPPER ALLOY
 - 1-3.CONTACT: PHOSPHOR BRONZE
- 2.PLATING SPECIFICATION:
 - G/F PLATING OVER NI
 - 100u"SN PLATED ON SOLDER TALL AREA
 - 50u"NI UNDER PLATED OVER ALL
 - 2-1.SHELL: Ni 30u" MIN PLATING OVER ALL
 - 2-2.LED: TIN PLATING OVER ALL
- 3.MECHANICAL PERFORMANCE:
 - 3-1.INSERTION FORCE: 22N MAX
 - 3-2.REMOVAL FORCE: 22N MAX
 - 3-2.DURABILITY: 750 CYCLES MIN.
- 4.ELECTRICAL PERFORMANCE:
 - 4-1.CURRENT RATING:1.5A
 - 4-2.VOLTAGE RATING:125V MAX
 - 4-3.CONTACT RESISTANCE: 40mΩ Max.
 - 4-4.INSULATION RESISTANCE: 500MΩ MIN
 - 4-5.DIELECTRIC WITHSTANDING VOLTAGE: 500V AC Min
- 5.ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -40°C~+85°C.
- 6.PACKAGE SPEC:TRAY

P/N:

WLR4F9-08 8 X X X 032

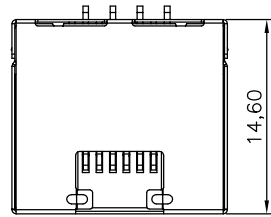
PLATING:

- 1-G/F
- 2-Au 3u"
- 3-Au 6u"
- 5-Au 15u"
- 6-Au 30u"

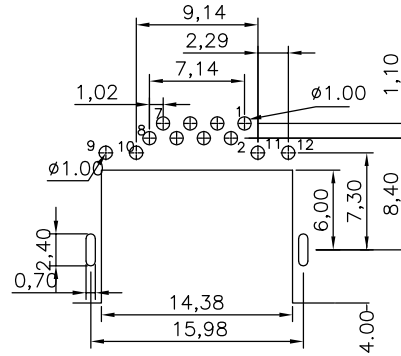
LED:

- 1-LEFT:YELLOW
- RIGHT:GREEN
- 2-LEFT:GREEN
- RIGHT:YELLOW

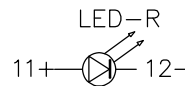
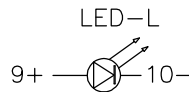
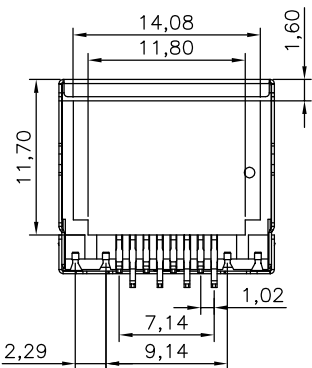
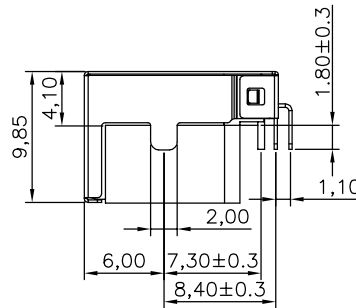
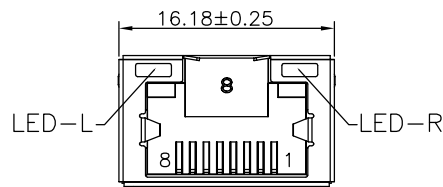
COLOUR:
A-BLACK
E-YELLOW



14,60



PCBLAYOUT
TOL:±0.05



| REV. | REVISION RECORD | DATE | GENERAL TOLERANCES | | SCALE: | NAME | DATE | PART.NO: | DWG.NO: |
|------|-----------------|----------|--------------------|----------|----------|-------------|----------|---------------------------------|------------|
| A0 | NEW RELEASE | 21.01.13 | LINEAR | ANGLES | 1:1 | Wang_jr | 21.01.13 | WLR4F9-088XXX032 | ENDE05 |
| | | | 0.0±0.35 | X°REF±6° | APPROVED | Han_Gao | 21.01.13 | TITLE: RJ45 8P8C DIP沉板式4.1MM | |
| | | | 0.00±0.25 | X°±3° | DESIGNER | Zijun_Huang | 21.01.13 | | |
| | | | 0.000±0.10 | X°X' ±2° | DRAWN | | | | |
| | | | UNIT:mm | | | | | REV: A0 | SHEET: 1/1 |
| | | | SIZE: A4 | | | | | | |